

HSF

NOTES:

Current Rating:5.0A AMP

Contact Resistance:10milliohm Max

Withstand Voltage:1000V AC/Minute

Insulation Resistance:1000Megohm Min

Operation Temperature:-25℃ to +85℃

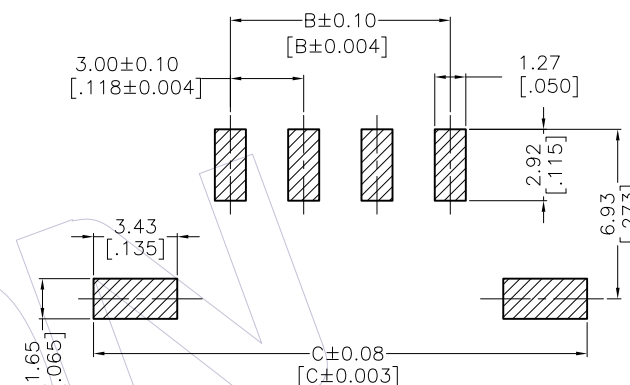
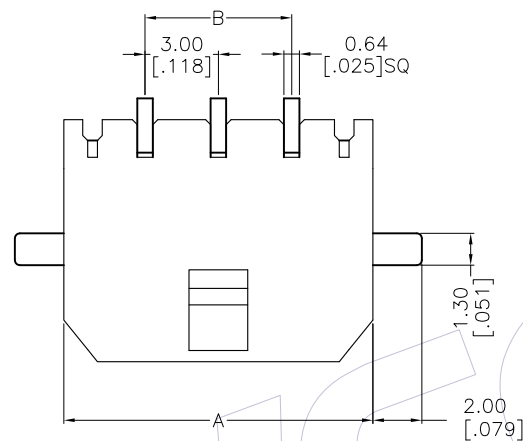
Housing Material:LCP+30%GF(UL94V-0)

Contact Material:Copper alloy

Contact plating: Au/Sn over Ni Plating

RECOMMENDED PCB LAYOUT

TOLERANCE IS ± 0.05



Ordering Information

WF3001-1 WZ XX B X 3

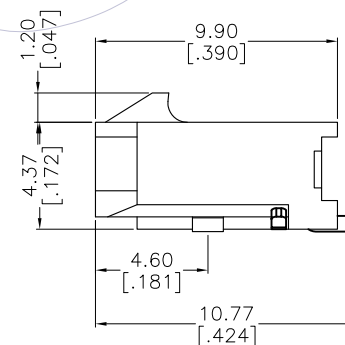
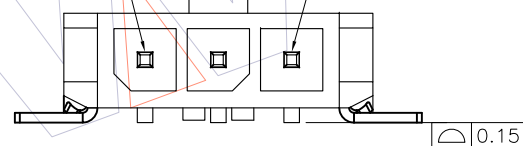
Terminal shape:
WZ:Wafer 90° SMT

NO.of Pins
02~12Pin

Packing:
0=PE Bag
T=Tube
A=Tray
R=Tape&Reel

Last Circuit

Circuit 1



Circuit	A	B	C
02	9.65[0.380]	3.00[0.118]	14.20[0.559]
03	12.65[0.498]	6.00[0.236]	17.20[0.677]
04	15.65[0.616]	9.00[0.355]	20.20[0.795]
05	18.65[0.735]	12.00[0.473]	23.20[0.913]
06	21.65[0.853]	15.00[0.591]	26.20[1.031]
07	24.65[0.971]	18.00[0.709]	29.20[1.150]
08	27.65[1.089]	21.00[0.827]	32.20[1.268]
09	30.65[1.207]	24.00[0.945]	35.20[1.386]
10	33.65[1.325]	27.00[1.063]	38.20[1.504]
11	36.65[1.443]	30.00[1.181]	41.20[1.622]
12	39.65[1.561]	33.00[1.299]	44.20[1.740]

				OPERATION		DRAW FZY	DATE 2015.05.02	SCALE	1:1	PART NO. WF3001-1WZXXBX3	
				X.X	±0.40			UNIT	mm inch		
A1	3012.05.03	料号由WF3001-1WZHXBX3变更为WF3001-1WZXXBX3		X.XX	±0.25	CHECK	DATE	SIZE	A4	TITLE: 3.0 Wafer Single Row 90° SMT With Latch	
A0	2011.12.20	NEW	-	X.XXX	±0.15			SHEET	1/1		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle DIM	± 3° TOL	APPROVE	DATE	PROJ.		Customer NO.	